Product/Process Change Notice - PCN 09_0094 Rev. -

Analog Devices, Inc. Three Technology Way Norwood, Massachusetts 02062-9106

This notice is to inform you of a change that will be made to certain ADI products (see Material Report). Any issues with this PCN or requirements to qualify the change (additional data or samples) must be sent to ADI within 30 days of receiving this notification. The information contained within this PCN is considered proprietary and should not be shared outside of your company. ADI contact information is listed below.

PCN Title:	OP291 - Addition of top coat stress relief material, Die Overcoat or Polyimide for SOIC's
Publication Date:	20-May-2009
Samples Available Date:	19-Jun-2009
Effectivity Date:	30-Jun-2009 *(the earliest date that a customer could expect to receive changed material)*

Description Of Change

OP291 material may have Die Overcoat added as a stress relief option during assembly to the SOIC package. This option will allow for either Die Overcoat or Polyimide top Coat to be implemented.
No changes will occur to Molding Compound, Die Attach, Paddle, Wire Thickness.

Reason For Change

The use of either Die Overcoat or Polyimide Top Coat, provides better manufacturing flexibility.

Impact of the change (positive or negative) on fit, form, function & reliability

OP291 has used both Die Overcoat or Polyimide over the lifetime of the product. Besides the stress relief material, there are no difference in the fit, form, or function that would be seen by the end-user. The performance of the part matches the specification, allowing both options to be used.

Product Identification *(this section will describe how to identify the changed material)*

No top mark identification changes will occur. Date code and Assembly lot information will identify material. If a customer request identification of material, that can be provided on a individual basis.

Summary of Supporting Information

Qualification has been performed per Analog Devices specification ADI0012, Procedure for Qualification of New or Revised Processes or Products. See attached Qual Plan summary.

Supporting Documents

Attachment 1: ADI_PCN_09_0094_Rev_-_ADI_Qual Plan_ID7143 .doc

Attachment 2: ADI_PCN_09_0094_Rev_-_ADI_Qual Plan_ID6379.doc

For questions on this PCN, send email to the regional contacts below or contact your local ADI sales representitive

Americas:	PCN_Americas@analog.com	**Europe:**	PCN_Europe@analog.com	**Japan:**	PCN_Japan@analog.com
				Rest of Asia:	PCN_ROA@analog.com

Appendix A - Affected ADI Models					
Added Parts On This Revision - Product Family / Model Number (6)					
OP291 / OP291GS	OP291 / OP291GS-REEL	OP291 / OP291GS-REEL7	OP291 / OP291GSZ	OP291 / OP291GSZ-REEL	OP291 / OP291GSZ-REEL7

Appendix B - Revision History		
Rev	**Publish Date**	**Rev Description**
Rev. -	20-May-2009	Initial Release